

**AMENDMENTS TO THE CLAIMS**

Claim 1. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element including a substrate, wherein light radiates from a light emission surface of the substrate of said light emitting element, the light emission surface being provided on the substrate opposite to an electrode forming surface of the ~~substrate~~ light emitting element; and

a ~~an inorganic transparent structure~~ structure, mounted on the light emission surface of the substrate, wherein the transparent structure is optically connected with the entire light emission surface, ~~has and has~~ a light distribution characteristic based on a three-dimensional shape of the transparent structure, ~~wherein the transparent structure comprises a side surface through which to allow the light to be radiated from the light emission surface is discharged from the transparent structure, and is bonded to the substrate by a transparent adhesive layer.~~

Claim 2. (Canceled).

Claim 3. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a thickness of half that of the semiconductor light emitting element to twice the length of a shorter side of the semiconductor light emitting element.

Claim 4. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a microscopic uneven surface to diffuse light.

Claim 5. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a reflection layer formed on its surface.

Claim 6. (Previously presented) The light emitting apparatus according to claim 17, wherein:

one of the lead frames has a cup portion, and

the transparent structure is fixed on the cup portion through adhesive resin with light diffusion material mixed therein.

Claim 7. (Previously presented) The light emitting apparatus according to claim 17, wherein:

the electrodes do not transmit light.

Claim 8. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that includes a substrate and that radiates light from a light emission surface ~~provided~~ on the substrate of the semiconductor light emitting element opposite an electrode forming surface of the ~~substrate~~ light emitting element;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a an inorganic transparent structure that is mounted on the light emission surface of the substrate and optically connected with the entire light emission surface and that has a light distribution characteristic based on a three-dimensional shape of the transparent structure; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure, the light transmitting resin ~~including~~ comprising a phosphor to wavelength-convert light emitted from the semiconductor light emitting element,

wherein the transparent structure comprises a side surface through which ~~to allow the light to be~~ radiated from the light emission surface is discharged from the transparent structure, and is bonded to the substrate by a transparent adhesive layer.

Claim 9. (Currently amended) The light emitting apparatus according to claim 8, wherein:

the light transmitting resin ~~contains~~ comprises two or more ~~kinds of~~ phosphors.

Claim 10. (Previously presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises the substrate, a buffer layer, an

n-type semiconductor layer, a light-emitting layer, and a p-type semiconductor layer.

Claim 11. (Previously presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises a gallium nitride system compound semiconductor.

Claim 12. (Previously presented) The light emitting apparatus according to claim 1, wherein the transparent structure comprises a light transmitting material comprising at least one of SiO<sub>2</sub>, Al<sub>2</sub>O<sub>3</sub>, SiC, Si<sub>3</sub>N<sub>4</sub>, AlN, ZrO<sub>2</sub>, borosilicate glass, and alumino-silicate glass.

Claim 13. (Previously presented) The light emitting apparatus according to claim 1, wherein the substrate comprises sapphire.

Claim 14. (Canceled)

Claim 15. (Canceled)

Claim 16. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that includes a substrate and that radiates light from a light emission surface provided on the substrate of the semiconductor light emitting element opposite to an electrode forming surface of the ~~substrate~~ light emitting element;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a an inorganic transparent structure that is mounted on the light emission surface of the substrate and optically connected with the entire light emission surface and that has a light distribution characteristic based on a three-dimensional shape of the transparent structure; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure,

wherein the transparent structure comprises a side surface through which ~~to allow the~~

light ~~to be~~ radiated from the light emission surface is discharged from the transparent structure, and is bonded to the substrate by a transparent adhesive layer.

Claim 17. (Previously presented) The light emitting apparatus according to claim 1, further comprising lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires.

Claim 18. (Presently Presented) The light emitting apparatus according to claim 1, further comprising light transmitting resin that seals the semiconductor light emitting element and the transparent structure.

Claim 19. (Previously presented) The light emitting apparatus according to claim 8, wherein the transparent structure is mounted on the light emission surface of the substrate by an adhesive layer.

Claim 20. (Previously presented) The light emitting apparatus according to claim 16, wherein the transparent structure is mounted on the light emission surface of the substrate by an adhesive layer.

Claim 21. (Previously presented) The light emitting apparatus according to claim 1, wherein the side surface comprises an inclined plane.

Claim 22. (Previously presented) The light emitting apparatus according to claim 8, wherein the side surface comprises an inclined plane.

Claim 23. (Previously presented) The light emitting apparatus according to claim 16, wherein the side surface comprises an inclined plane.